



Haptics: Technology and Applications—2021

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Deadline for manuscript
submissions:

closed (31 October 2021)

Message from the Guest Editor

Dear Colleagues,

This Special Issue seeks papers which examine some of the latest advances with respect to haptic actuators, haptic rendering, haptic applications in virtual reality/augmented reality, haptic applications in virtual education/training, and all aspects of haptics, including neuroscience, psychophysics, perception, and interactions. This Special Issue also welcomes papers related to medical and surgical simulations, skills training, rehabilitation robotics, collaborative human–robot interactions, communication, and haptic feedback for design and the arts.

Prof. Dr. Sang-Youn Kim
Guest Editor





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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